

IN THE CLAIMS:

Please CANCEL without prejudice or disclaimer claims 1-21 the underlying PCT application and ADD new claims 22-42 in accordance with the following:

Claims 1-21 (canceled)

22. (new) An arrangement, comprising:
at least one substrate;
at least one electrical component arranged on a surface section of each substrate, each electrical component having an electrical contact surface; and
at least one electrical contact lug, each including
at least one electrically-conductive film having an electrical connection surface in electrical contact with the contact surface of at least one of said at least one electrical component, and
an area protruding beyond the contact surface of the at least one of said at least one electrical component.
23. (new) An arrangement according to claim 22, wherein the at least one electrically-conductive film is a laminated interconnect having at least two electrical conductor layers and at least one electrical insulation layer arranged between the at least two electrical conductor layers.
24. (new) An arrangement in accordance with claim 23, wherein the at least two electrical conductor layers and the insulation layer of the laminated interconnect are arranged to produce opposing magnetic fields in the at least two electrical conductor layers upon electrical activation.
25. (new) An arrangement according to claim 24, wherein the at least two electrical conductor layers of the laminated interconnect are substantially in a coplanar arrangement.
26. (new) An arrangement in accordance with claim 25, wherein the at least one electrical component is a power semiconductor chip.

27. (new) A method of producing an arrangement of at least one electrical component and at least one electrical contact lug, comprising:

providing a substrate with an electrical component having an electrical contact surface;
and

forming an electrical contact lug with an electrically-conductive film having a connection surface in contact with the electrical contact surface of the electrical component and an area protruding beyond the contact surface of the electrical component.

28. (new) A method in accordance with claim 27, further comprising bringing together the contact surface of the at least one electrical component and the connection surface of the electrically-conductive film using at least one of soldering, welding and gluing.

29. (new) A method in accordance with claim 28, further comprising forming the electrically-conductive film having the connection surface as a laminated interconnect with at least one electrical insulation layer and at least one electrical conductor layer.

30. (new) A method in accordance with claim 29, further comprising:
applying an electrical insulating film to the substrate and the electrical component; and
forming a window in the electrical insulating film to reveal the electrical contact surface of the electrical component.

31. (new) A method according to claim 30, wherein said applying of the electrical insulating film is performed in a vacuum.

32. (new) A method in accordance with claim 31, wherein the electrical insulating film is used as the at least one electrical insulating layer of the laminated interconnect of the electrically-conductive film.

33. (new) A method in accordance with claim 32, wherein said forming of the electrical conductor layer of the laminated interconnect comprises applying electrically-conductive material at least one of before and after said applying of the insulating film.

34. (new) A method in accordance with claim 33, said applying of the electrical insulating film creates an area of the insulating film protruding over the electrical contact surface of the electrical component.

35. (new) A method in accordance with claim 34, wherein the insulating film is formed of a plastic material based on at least one polyamide, polyethylene, polyphenol, polyether-etherketone and an epoxy.

36. (new) A method in accordance with claim 35, wherein the insulating film has a film thickness of 25 to 150 μm .

37. (new) A method in accordance with claim 36, further comprising tempering after said applying of the insulating film.

38. (new) A method in accordance with 37, further comprising repeating said applying of the electrical insulating film until the film thickness is obtained.

39. (new) A method in accordance with claim 35, wherein said forming of the window in the electrical insulating film comprises removing the insulating film by laser ablation.

40. (new) A method in accordance with claim 35,
wherein the electrical insulating film is a photo-sensitive insulating film is used, and
wherein said forming of the window in the electrical insulating film comprises a photo-lithographic process.

41. (new) A method in accordance with claim 33, said forming of the electrical conductor layer of the laminated interconnect comprises forming sublayers arranged one above another from different, electrically-conductive films.

42. (new) A method in accordance with claim 33, further comprising repeating at least one of said applying of the insulating film, forming of the window in the insulating film and forming of the electrical contact lug.